

Title (en)  
Method of fabricating a composite material

Title (de)  
Verfahren zur Herstellung von Kompositmaterial

Title (fr)  
Procédé pour fabriquer un matériau composite

Publication  
**EP 0446934 B1 19980923 (EN)**

Application  
**EP 91103974 A 19910314**

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Abstract (en)  
[origin: EP0446934A2] In order to obtain a composite material excellent in the bonding strength (adhesion) of two materials and thermal conductivity, the invention presents a fabricating method of a composite material by compounding a high melting material W and a low melting material Cu, which comprises, a first step (1, 2, 3) of forming pores in the high melting material W, having the porosity distribution so that the porosity may be large at least in part of the surface thereof and that the porosity may gradually increase toward that part, and a second step (4) of infiltrating the low melting material Cu from the large porosity part of the material obtained in the first step (1, 2, 3), wherein the composition ratio of the high melting material and low melting material is in a gradient distribution. <IMAGE>

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